超眾科技股份有限公司
Chaun-Choung Technology Corp.

Date: Aug. 27th, 2020

Chaun-Choung Technology Corporation

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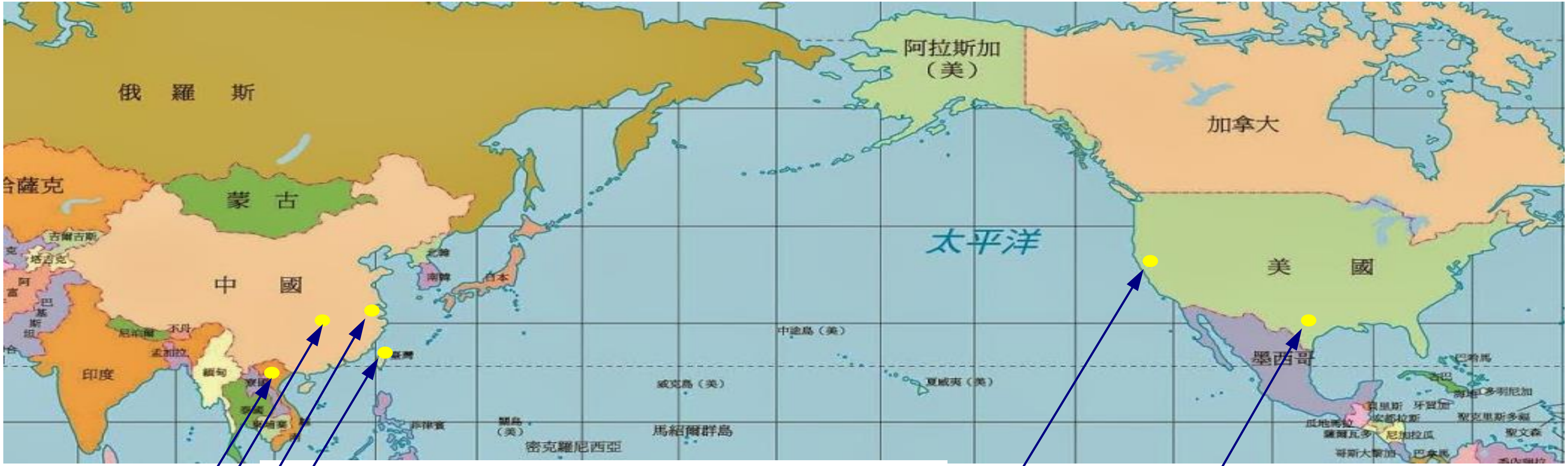
Company Profile

- **Headquarters :** Chaun-Choung Technology Corp.
- **Founded :** Dec.14. 1973
- **Nidec:** Hold 62.71% shares, as a major shareholder (Until Aug. 17th, 2020).
- **Address :** No. 184-3, Zhongxing N. St., Sanchong Dist., New Taipei City 241, Taiwan
- **Capital :** NT$ 863,434 (K)
- **Main Business :** Heat Sink & Thermal Solutions
- **WW Factories & Offices**

WW Factories & Offices



CHAUN CHOUNG TECHNOLOGY
New Taipei City, Taiwan

JUE-CHOUNG ELECTRONICS-
Kunshan Jiangsu, China

CYUNSIANG HIGH TECH – Chongqing, China

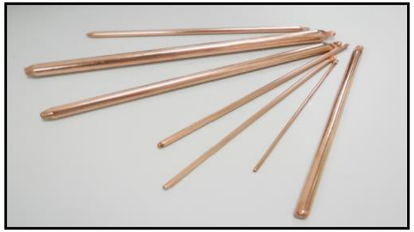
NIDEC CHAUN CHOUNG VIETNAM Corp. – Hanoi, Vietnam

CCI AMERICA INC- Austin, USA

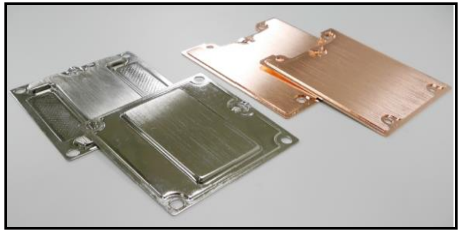
CCI AMERICA INC- CA, USA

Main Products

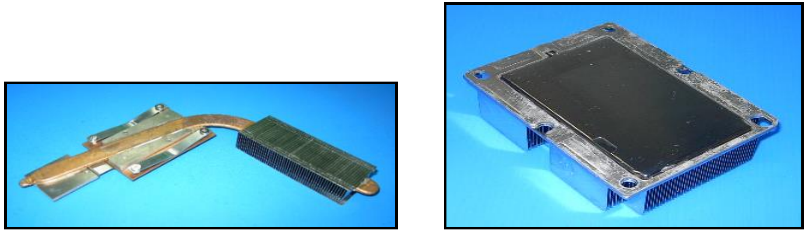
- Heat Pipe



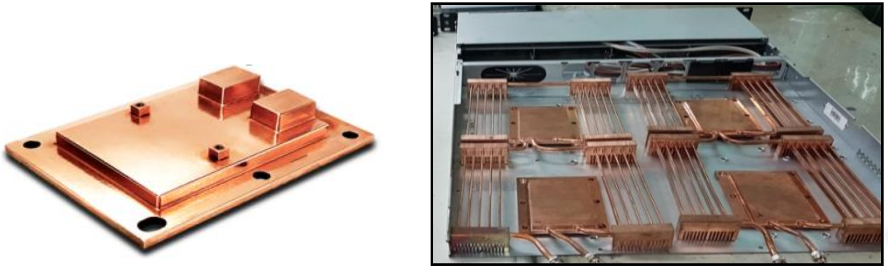
- Vapor Chamber



- Thermal Module



- Cold Plate



- CDU

Main Products

Smartphone application

Thermal Solution Features:

- Ultra Thin
- Lightweight
- Preventing Local Hot Spot
- High Thermal Conductivity

Notebook module

Thermal Solution Features:

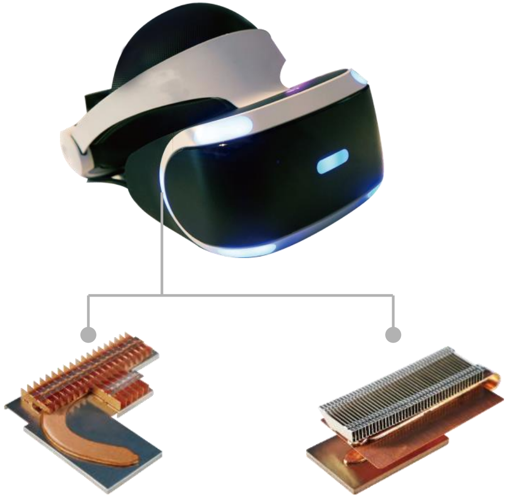
- Protecting CPUs from Constant High Loading Operations
- Slim Modules Available
- Supporting Multi-Chip Applications

Portable application

Thermal Solution Features:

- Excellent Thermal Conductivity
- Alleviate Hot Spot Issue
- Thin Layout Applications

Main Products



VR application

Thermal Solution Features:

- Light
- Low Thermal Resistance

Desktop module

Thermal Solution Features:

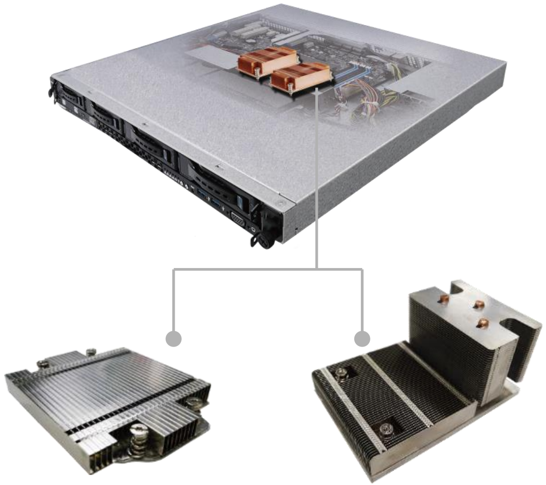
- Meeting All Form factor Requirements
- Moderating Cost

Gaming application

Thermal Solution Features:

- High Thermal Capacity

Main Products



Server module

Thermal Solution Features:

- Meeting High Power CPU Requirements
- Complete Product Line Covering All Form factors

Switch application

Thermal Solution Features:

- High Reliability
- Long Durability
- Easy Installation

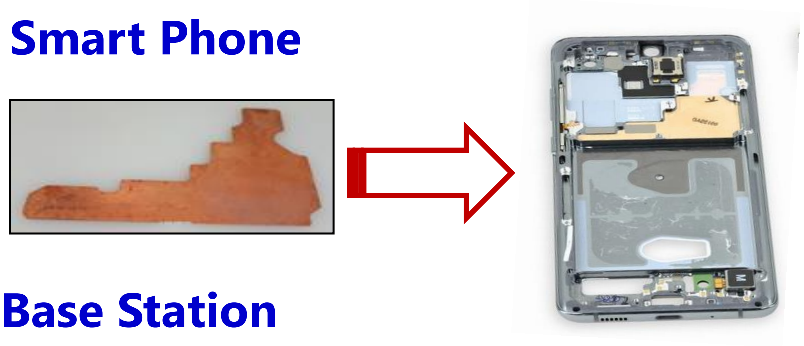
Liquid cooling application

Thermal Solution Features:

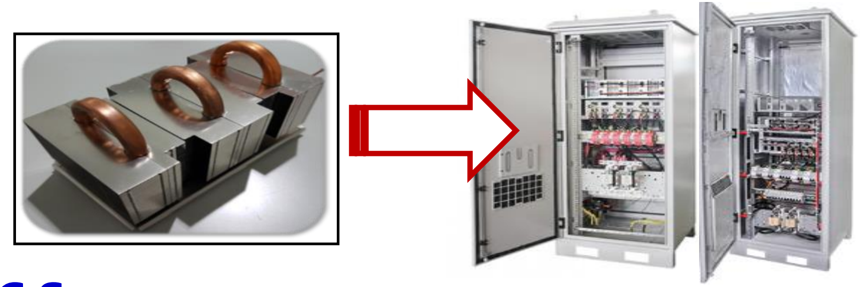
- Low Noise Level
- Energy Saving
- Excellent Performance for High Power Application

Focus Developing Products

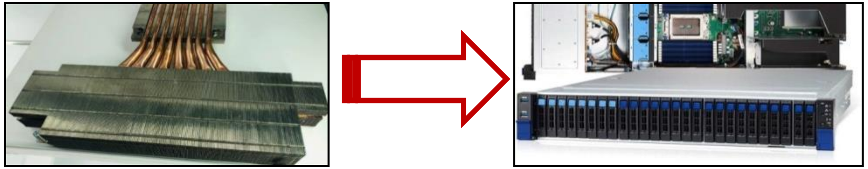
- **Ultra-thin Thermal Solution for 5G Smart Phone**
  - VC Thickness 0.25mm – 0.35mm



- **Hi-power Thermal Solution for 5G Base Station**
  - 3D VC >700W

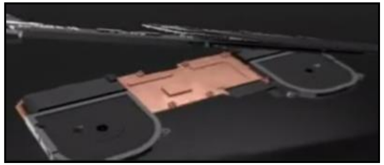


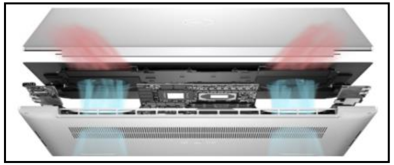
- **Hi-Power Thermal Solution for HPC Server**
  - Large Diameter HP > 350W



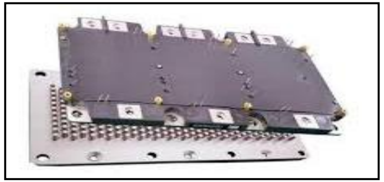
Focus Developing Products

- **Slim Thermal Solution for Gaming NB**
  - VC > 120W

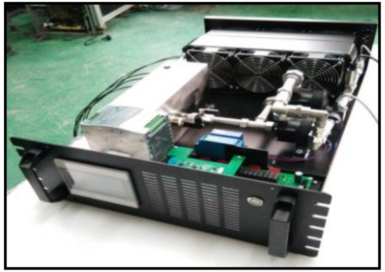




- **Rugged Thermal Solution for Automation**
  - VC + Liquid Cooling ~ 45KW



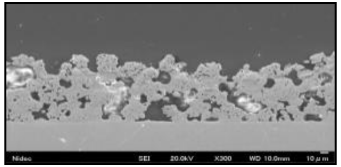
- **Liquid Cooling Solution for Rack / Tower Server**
  - CDU ≤5U



Competitive Advantages

- **Metallurgy & Wick Technology –**

  Nidec & CCI team with strong basic research to support Ultra-thin / Hi-power Thermal Solutions.

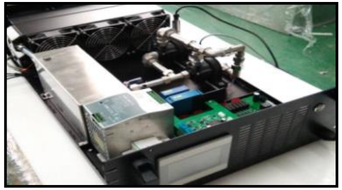


- **Automation Equipment Building in House –**

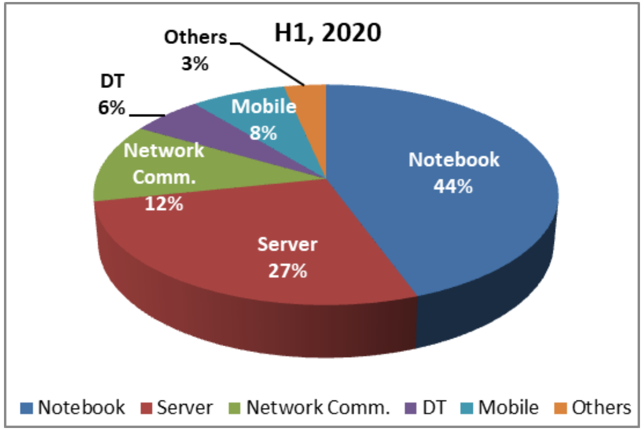
  Nidec & CCI team develop manufacturing machine from sample to mass production know-how in house.

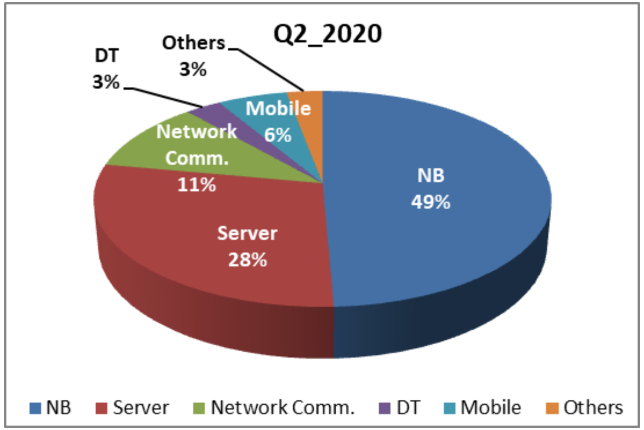
- **Active & Passive Horizontal Division of Collaborating –**

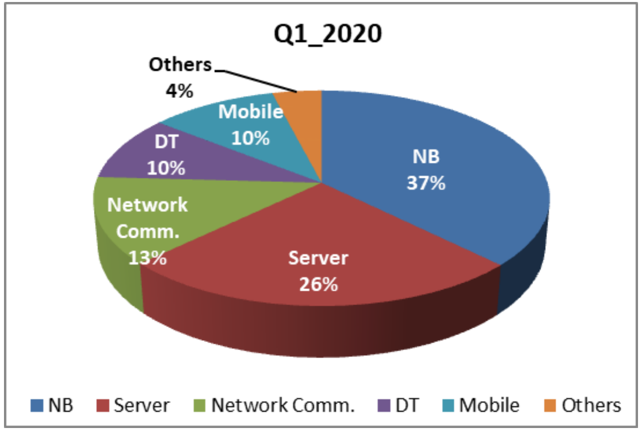
  Nidec is good at Fan/Pump active solution and CCI is good at HP/VC passive solution, collaboration to provide customer total solution with best options.



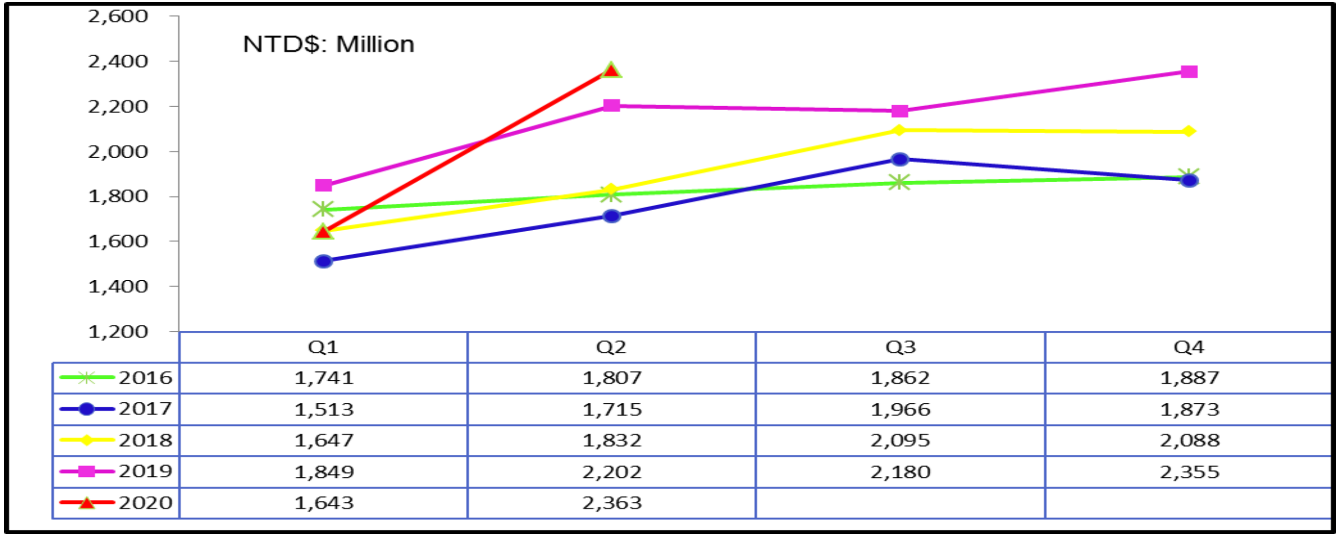
Product Lines







Revenue

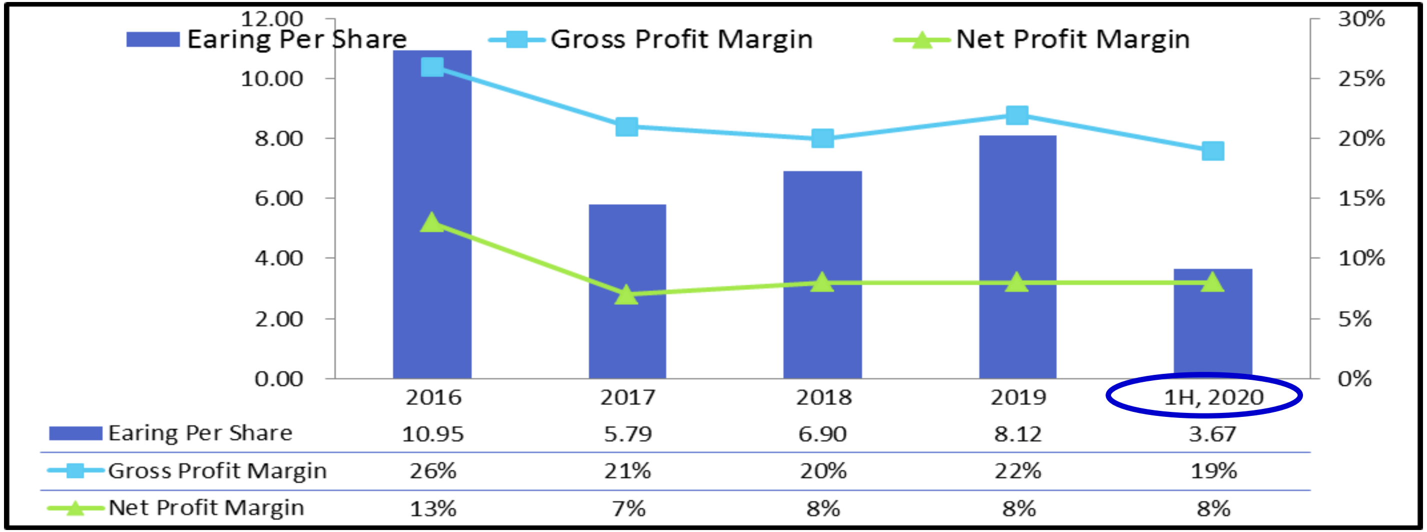


	Q1	Q2	Q3	Q4
2016	1,741	1,807	1,862	1,887
2017	1,513	1,715	1,966	1,873
2018	1,647	1,832	2,095	2,088
2019	1,849	2,202	2,180	2,355
2020	1,643	2,363		

	Q1	Q2	Q3	Q4	Total
2016	1,741	1,807	1,862	1,887	7,297
2017	1,513	1,715	1,966	1,873	7,067
2018	1,647	1,832	2,095	2,088	7,662
2019	1,849	2,202	2,180	2,355	8,586
2020	1,643	2,363			4,006

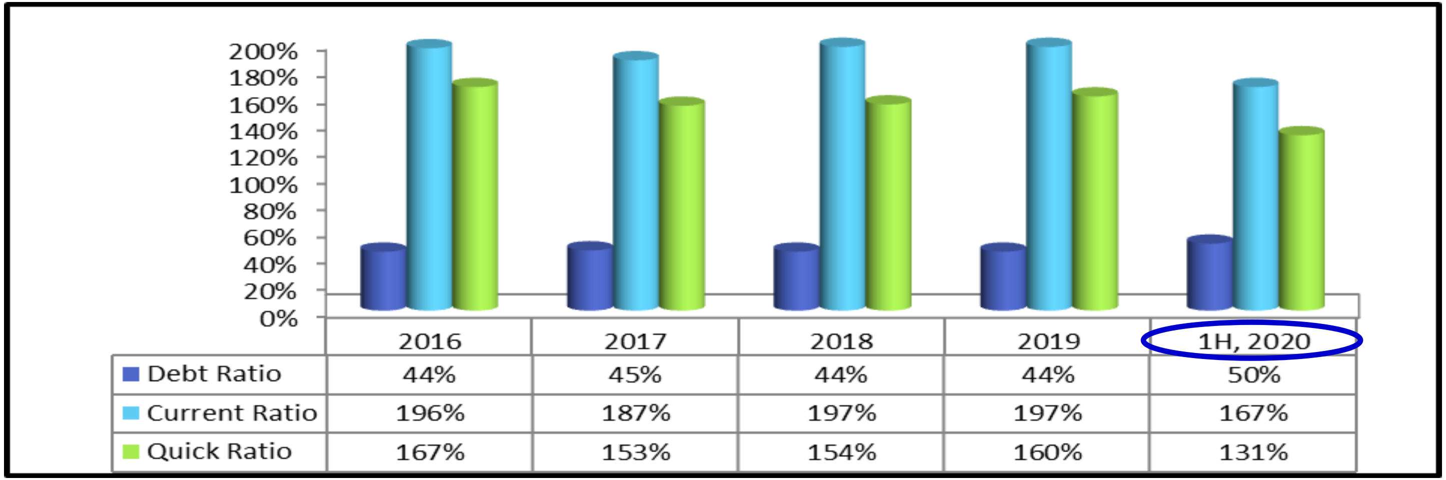
NTD$: Million

Financial Index I.



Years / Items	2016	2017	2018	2019	1H, 2020
Earing Per Share	10.95	5.79	6.90	8.12	3.67
Gross Profit Margin	26%	21%	20%	22%	19%
Net Profit Margin	13%	7%	8%	8%	8%

Financial Index II



	2016	2017	2018	2019	1H, 2020
■ Debt Ratio	44%	45%	44%	44%	50%
■ Current Ratio	196%	187%	197%	197%	167%
■ Quick Ratio	167%	153%	154%	160%	131%

Years / Items	2016	2017	2018	2019	1H, 2020
Debt Ratio	44%	45%	44%	44%	50%
Current Ratio	196%	187%	197%	197%	167%
Quick Ratio	167%	153%	154%	160%	131%

Nidec

All for dreams